

Customer:

Project Name:

Date:

1. Robot working environment

Atmosphere: In Vacuum (chamber):

2. Robot environment requirements

Class Temperature Wet: Dry:

3. What type of substrate do you handle

Wafer: Reticle: Flat Panel: Other:

If other, please specify:

4. What is the substrate size

2" (50 mm): 3" (75mm): 4" (100mm): 5" (125 mm): 6" (150 mm):

8" (200 mm): 12" (300mm):

Non-standard wafer sizes:

5. Substrate details

Material Thickness Weight

Temperature Other specifications

6. Substrate warp

No Warp:  Smile:  Frown:  Potato Chip: 

Maximum Warp Size

- 7. Please provide a layout sketch with basic dimensions in top and side views, including substrate pick and place positions, arrangement, any obstacles to avoid, any restrictions for installing the robot (top or bottom mounting).
- 8. Please provide a basic description of the process and motion sequence for material handling.

9. What is your performance requirement based on the handling sequence

(wafers per hour, time requirement for wafer pick, place or swap)

10. What are your repeatability requirements by axes

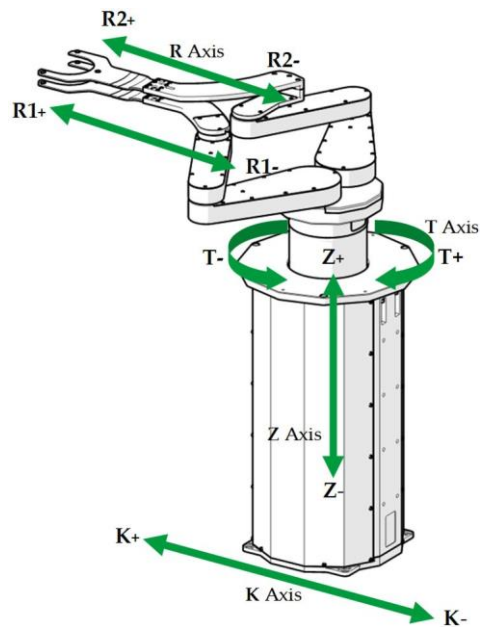
R axis

Z axis

T axis

Y axis

K axis



11. What are your accuracy requirements for X and Y at a predefined distance from the robot

X axis Y axis

12. What kind of end-effector do you need

Vacuum Paddle: Gravity Pan: Gripping:

13. Does the process require wafer flipping

Flipping: No Flipping:

14. Any restrictions regarding the material of the paddle?

15. Do you have specific scanning requirements

16. Do you have specific software requirements

Legacy Emulation: Backwards Compatibility:

Other

17. Do you need a teach pendant terminal

Yes, with E-Stop: Yes, E-Stop & "Liveman" switch: No:

18. How do you intend to communicate with the robot

RS232: Ethernet:

19. Do you need a Prealigner

Yes: No:

20. If you have any other requirements or comments, please list them here: